





# **Emerging Technologies** & Factory Automation

23rd IEEE International Conference September 4-7, 2018, Torino, Italy

September 4 - 7, 2018, Torino, Italy

### **Call for Papers**

## Track 10 - New frontiers in Automation: Cyber-Physical Systems and Artificial Intelligence

Track co-chairs

Tullio Facchinetti, University of Pavia, Italy, <a href="mailto:tullio.facchinetti@unipv.it">tullio.facchinetti@unipv.it</a>
Oliver Niggeman, Institut für industrielle Informationstechnik, Hochschule Ostwestfalen-Lippe,
Germany oliver.niggemann@iosb-ina.fraunhofer.de

**Focus**: Focus of this track is on methods, technologies and case studies which leverage on cyber-physical systems and artificial intelligence to provide smart capabilities such as self-configuration, self-optimization and self-diagnosis.

**Topics** Distributed Architectures for Adaptive Systems; Autonomous Cyber-Physical Systems; Networked Adaptive Systems; Self-Adaption and Self-Organization for Smart Factories, Smart Cities, Smart Buildings and Smart Energy; Intelligent Interfaces to Smart Distributed Systems, Al-Powered Smart Interfaces; Learning and Self-Optimizing Cyber-Physical Systems; Machine Learning for Production; Deep Learning for Industrial Applications; Algorithms for Diagnosis and Repair; Automatic Adaption; Planning and Scheduling.

Aim: The ETFA conference brings together experts from industry and academia to disseminate novel ideas and emerging trends, research results and practical achievements in the area of industrial and factory automation. The ultimate goal is fostering the development and adoption of scientific methods, models, and tools for the efficient design and operation of industrial and factory automation systems.

**Submission of Papers**: The working language of the conference is English. Two types of submissions are solicited. Long Papers – limited to 8 double column pages in a font no smaller than 10-points. Work-in-Progress– limited to 4 double column pages in a font no smaller than 10-points. Manuscripts must be submitted electronically in PDF format, according to the instructions contained in the Conference web site http://ieee-etfa2018.com/.

Best Paper Award: Best paper awards in Factory Automation and Emerging Technologies will be presented at the conference banquet dinner

Further Information: Conference website: http://ieee-etfa2018.com/. ETFA2018 Conference Secretariat: etfa2018@ieiit.cnr.it

**Submission of Papers**: The working language of the conference is English. Two types of submissions are solicited. Long Papers – limited to 8 double column pages in a font no smaller than 10-points. Work-in-Progress– limited to 4 double column pages in a font no smaller than 10-points. Manuscripts must be submitted electronically in PDF format, according to the instructions contained in the Conference web site http://ieee-etfa2018.com/

Paper Acceptance: Each accepted paper must be presented at the conference by one of the authors; otherwise the ETFA2018 Organizing Committee reserves the right to exclude a paper from distribution after the conference at IEEE Xplore. The final manuscript must be accompanied by a registration form and a registration fee payment proof. All conference attendees must pay the conference registration fee and their travel expenses.

#### registration fee and the

### Author's Schedule (NEW!!!):

Regular and special sessions papers
Submission deadline:
Acceptance notification:
Deadline for final manuscripts:

April 27, 2018
June 1, 2018
July 6, 2018

Work-in-progress papers Submission deadline: Acceptance notification: Deadline for final manuscripts:

June 11, 2018 June 25, 2018 July 6, 2018

http://ieee-etfa2018.com/

Sponsors:





#### **Track Program Committee**

Mohammad Al Faruque - University of California

Luis Almeida - Universidade do Porto Alessandro Biondi - Scuola Superiore Sant'Anna

Gautam Biswas - Vanderbilt University Giorgio Buttazzo - Scuola Superiore Sant'Anna

Jens Eliasson - Lulea TU

Franco Fummi - Università di Verona Mikael Gidlund - Mid Sweden University Meir Kalech - Ben-Gurion University of the Negev

Stamatis Karnouskos - SAP Zhaodan Kong - University of California

Heiko Krumm - TU Dortmund Milos Manic - Virginia Commonwealth

Mauro Marinoni - Scuola Superiore

Mark Mattingly-Scott - IBM Alessio Micheli - Università di Pisa Marco Piastra - University of Pavia

Thilo Steckel - Claas Borahan Tumer - Marmara Uni Orfefs Voutyras - ICCS/NTUA

With the support of:

